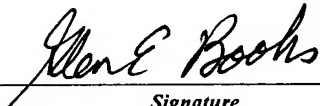
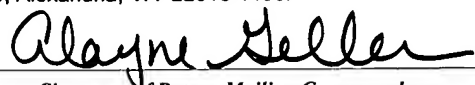


Image

1753

TRANSMITTAL OF FORMAL DRAWINGS				Docket No. Khaselev 2-2-28	
In Re Application Of: <b>O. KHASELEV et al.</b>					
Serial No. 10/050,014	Filing Date 01/17/2002	Confirmation No. 5508	Examiner WONG, EDNA	Art Unit 1753	
Invention: <b>ELECTROPLATING SOLUTION FOR HIGH SPEED PLATING OF TIN-BISMUTH SOLDER</b>					
Address to: Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450					
Transmitted herewith are:  ONE (1) sheets of formal drawing(s) for this application.  <input checked="" type="checkbox"/> Each sheet of drawing indicates the identifying indicia suggested in 37 CFR Section 1.84(c).					
 Signature			Dated: 01/07/2004		
<b>GLEN E. BOOKS</b> REG. NO. 24,950  <b>LOWENSTEIN SANDLER PC</b> 65 LIVINGSTON AVENUE ROSELAND, NEW JERSEY 07068 973-597-6162			<div>I certify that this document and attached formal drawings are being deposited on 01/07/2004 with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.</div> <div> Signature of Person Mailing Correspondence</div> <div><b>ALAYNE GELLER</b> Typed or Printed Name of Person Mailing Correspondence</div>		